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APPLICATION NO.		FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/786,825	10/786,825 02/25/2004		Belgacem Haba	TESSERA 3.0-337 II	5077
38091	7590	09/15/2006		EXAMINER	
TESSERA	A VIID . 4	. 1	FULK, STEVEN J		
LERNER DAVID et al. 600 SOUTH AVENUE WEST				ART UNIT	PAPER NUMBER
WESTFIEL	D, NJ 0	7090	2891		
				DATE MAILED: 09/15/2006	

Please find below and/or attached an Office communication concerning this application or proceeding.

		Application No.	Applicant(s)					
		10/786,825	HABA ET AL.					
	Office Action Summary	Examiner	Art Unit					
		Steven J. Fulk	2891					
Period fo	The MAILING DATE of this communication appears on the cover sheet with the correspondence address Period for Reply							
WHIC - Exter after - If NC - Failu Any	ORTENED STATUTORY PERIOD FOR REPLECTION OF THE MAILING INSIDE OF THE MAILING INSIDE OF THE MAILING INSIDE OF THE MAILING INSIDE OF THE OF THE MAILING INSIDE OF THE	DATE OF THIS COMMUNICATION .136(a). In no event, however, may a reply be a distributed will apply and will expire SIX (6) MONTHS from the course the application to become ABANDON	DN. timely filed m the mailing date of this communication. IED (35 U.S.C. § 133).					
Status								
1)⊠	Responsive to communication(s) filed on 26.	June 2006.						
2a) <u></u> □	☐ This action is FINAL. 2b) ☐ This action is non-final.							
3) 🗌	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is							
	closed in accordance with the practice under	Ex parte Quayle, 1935 C.D. 11,	453 O.G. 213.					
Dispositi	on of Claims							
5)□ 6)⊠ 7)□	Claim(s) 1-32 is/are pending in the application 4a) Of the above claim(s) 22-32 is/are withdra Claim(s) is/are allowed. Claim(s) 1-21 is/are rejected. Claim(s) is/are objected to. Claim(s) are subject to restriction and/	awn from consideration.						
Applicati	on Papers							
·	The specification is objected to by the Examin The drawing(s) filed on 25 February 2004 is/a Applicant may not request that any objection to the	re: a)⊠ accepted or b)□ object	•					
11)	Replacement drawing sheet(s) including the correct The oath or declaration is objected to by the E		• •					
Priority ι	ınder 35 U.S.C. § 119							
12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) All b) Some * c) None of: 1. Certified copies of the priority documents have been received. 2. Certified copies of the priority documents have been received in Application No. 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received.								
Attachmen	t(s)							
2) Notice 3) Information	te of References Cited (PTO-892) te of Draftsperson's Patent Drawing Review (PTO-948) mation Disclosure Statement(s) (PTO/SB/08) tr No(s)/Mail Date	4) Interview Summal Paper No(s)/Mail 5) Notice of Informal 0) Other:	Date					

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DETAILED ACTION

Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- 2. Claims 1-7, 12-17 and 21 are rejected under 35 U.S.C. 102(b) as being anticipated by Glenn '644.

Regarding claim 1, Glenn discloses a method of making mountable MEMS devices comprising assembling a portion of a wafer having a main surface and a multiplicity of spaced-apart caps projecting upwardly from the main surface (fig. 2B, 42) and having channels between the caps (16); a terminal bearing element incorporating an array of terminals (fig. 3, 44); and electrically connecting the terminals by bonding leads extending to contacts on the wafer disposed in the channels (46).

Regarding claim 2, the reference further discloses the terminal-bearing element (fig. 3, 44) to include the lead (46), and bonding the leads to the contacts (16).

Regarding claim 3, the reference further discloses the leads to be aligned with the channels (lead 46 must be aligned with channel/contact 16 in order to electrically connect to contact).

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Regarding claim 4, the reference further discloses the leads (fig. 3, 46) to extend at a level above the contacts (16), and the leads bend down to engage the contact.

Regarding claims 5 and 6, the reference further discloses the channels to include wide channels (32) and narrow channels (34), and contacts disposed in the wide channels with leads aligned to the channels (MEMS device 14 would inherently have electrical contacts of some length (elongated) and aligned with channel 32).

Regarding claim 7, the reference further discloses severing the wafer in the channels (fig. 2B, 20; singulation streets) to form a plurality of units, each unit containing a cap, a terminal, and a contact (fig. 3).

Regarding claim 12, the reference further discloses the wafer to include a plurality of MEMS devices (fig. 3, 14), and the caps to cover the MEMS devices.

Regarding claim 13, Glenn discloses a method of making electronic devices comprising assembling a portion of a wafer having a main surface (fig. 2A, 42), structure defining an upper surface above the main surface, depressions extending into the wafer from the upper surface (32 and 34) and contacts in the depressions (16 in depression 34); and a terminal bearing element incorporating an array of terminals so as to mount a plurality of terminals simultaneously (fig. 3, 44); and electrically connecting the terminals by bonding leads extending to contacts on the wafer disposed in the depressions (46).

Regarding claim 14, the reference further discloses the terminal-bearing element (fig. 3, 44) to include the lead (46), and bonding the leads to the contacts (16).

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Regarding claim 15, the reference further discloses the leads to be aligned with the depressions (lead 46 must be aligned with depression/contact 16 in order to electrically connect to contact).

Regarding claim 16, the reference further discloses the leads (fig. 3, 46) to extend at a level above the contacts (16), and the leads bend down to engage the contact.

Regarding claim 17, the reference further discloses severing the wafer in the channels (fig. 2B, 20; singulation streets) to form a plurality of units.

Regarding claim 21, the reference further discloses the structure defining the upper surface to include a plurality of spaced-apart caps defining the depressions as channels extending between caps (fig. 2A, channel/depressions 32 and 34 between upper surface 42).

Claim Rejections - 35 USC § 103

- 3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 4. Claims 8-10 and 18-20 are rejected under 35 U.S.C. 103(a) as being unpatentable over Glenn in view of Haba et al. '910.

Glenn teaches all of the elements of the claims as set forth in paragraph 2 above, but Glenn does not explicitly teach using a lead frame that includes a dielectric layer and terminals electrically connected to each other prior to assembly

as the terminal-bearing element. Haba et al. teaches a method of making electrical connections in microelectrical devices using breakable lead frame sections, wherein the lead frame terminal is mounted on top of the device (fig. 12; col. 11, lines 17-20); the lead frame is supported by a dielectric layer (fig. 12, 112); the terminals (118, 130) are separated from each other by severing the leads (128) and bending the leads to engage with the contacts in the channels (172).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to use the lead frame system of Haba et al. to electrically connect the MEMS device of Glenn. One would have been motivated to do this because using a lead-frame to electrically connect devices to peripheral circuitry was well known to be a faster process than using individual wire bonds, thus improving the manufacturing process and reducing the cost of manufacturing.

5. Claim 11 is rejected under 35 U.S.C. 103(a) as being unpatentable over Glenn '644 in view of Kim et al. '206.

Glenn teaches all of the elements of the claim including a making a mountable MEMS device having a membrane and a cavity (col. 1, lines 11-21), but does not explicitly teach the MEMS device being acoustically-active. Kim et al. teaches a method of making a mountable, acoustically-active device (surface acoustic wave filter).

It would have been obvious to one of ordinary skill in the art at the time the invention was made for the device of Glenn to be used as an acoustically-active device as described by Kim et al. One would have been motivated to do this because surface acoustic wave filters are conventional MEMS devices having a

membrane and cavity that are frequently used in RF and IF commercial applications (Kim et al., col. 1, lines 16-22).

Response to Arguments

- 6. Applicant's arguments with respect to claims 1-4, 6-7, 12-17 and 21 have been considered but are moot in view of the new ground(s) of rejection as set forth above.
- 7. Applicant's arguments with respect to claims 8-10 and 18-20 have been fully considered but they are not persuasive.

Applicant argues that Haba et al. does not teach the terminal bearing element to be electrically connected prior to the assembly step. However, Haba et al. teaches the connection section (fig. 12, 130; read as a terminal) to be electrically connected prior to the assembly step, and when combined with Glenn as described above, the severing step of Glenn would sever at least some connections between the terminals.

Conclusion

8. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure.

Johnson et al. '417, Bureau et al. '194, Bradley et al. '664, and Weekamp et al. '163 disclose methods of making mountable, acoustically-active MEMS devices.

Grube et al. '863, DiStefano et al. '239, Miyazaki et al. '215, and Jiang et al. '456 disclose methods of attaching electrical circuit devices using breakable lead-frames.

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9. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Steven J. Fulk whose telephone number is (571) 272-8323. The examiner can normally be reached on Monday through Friday, 9:30am to 6:00pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Bill Baumeister can be reached on (571) 272-1722. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

10. Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

SIA

Steven J. Fulk Patent Examiner Art Unit 2891

September 8, 2006

BRADLEY K. SMITH PRIMARY EXAMINER